



Product Change Notification

#113039- 00

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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

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Product Change Notification

Change Notification #: 113039 - 00
Change Title: Intel® Xeon® Processor E3-1281 v3, PCN 113039-00, Product Design
Date of Publication: May 22, 2014

Key Characteristics of the Change:

Product Design

Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material:	June 2, 2014
Date of First Availability of Post-Conversion Material:	June 2, 2014

The date of "First Availability of Post-Conversion Material" is the projected date that a customer may expect to receive the Post-Conversion Materials. This date is determined by the projected depletion of inventory at the time of the PCN publication. The depletion of inventory may be impacted by fluctuating supply and demand, therefore, although customers should be prepared to receive the Post-Converted Materials on this date, Intel will continue to ship and customers may continue to receive the pre-converted materials until the inventory has been depleted

Description of Change to the Customer:

Intel will be raising the tested Thermal Design Power (TDP) value from 80W to 82W on the Intel® Xeon® Processor E3-1281 v3 in order to align the processor to the published product specifications.

Customer Impact of Change and Recommended Action:

Intel anticipates no change or impact to customer platforms designed to Intel guidelines. Existing 80W tested TDP parts are fully functional in all respects, but may be power limited under extreme power and temperature workloads.

Customers should be ready to receive the new material by the "Date Customer Must be Ready to Receive Post-Conversion Material" as shown above in the milestones above. Please contact your Intel Field Sales Representative with any questions, requests or concerns.

Products Affected / Intel Ordering Codes:

Pre-Conversion						Post Conversion		
Marketing Name	Processor#	Frequency	Product Code	S-Spec	MM#	Product Code	S-Spec	MM#
Intel® Xeon® Processor	E3-1281 v3	3.70 GHz	CM8064601575329	SR1R2	932024	CM8064601575329	SR21F	937354

PCN Revision History:

Date of Revision: May 22, 2014	Revision Number: 00	Reason: Originally Published PCN
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